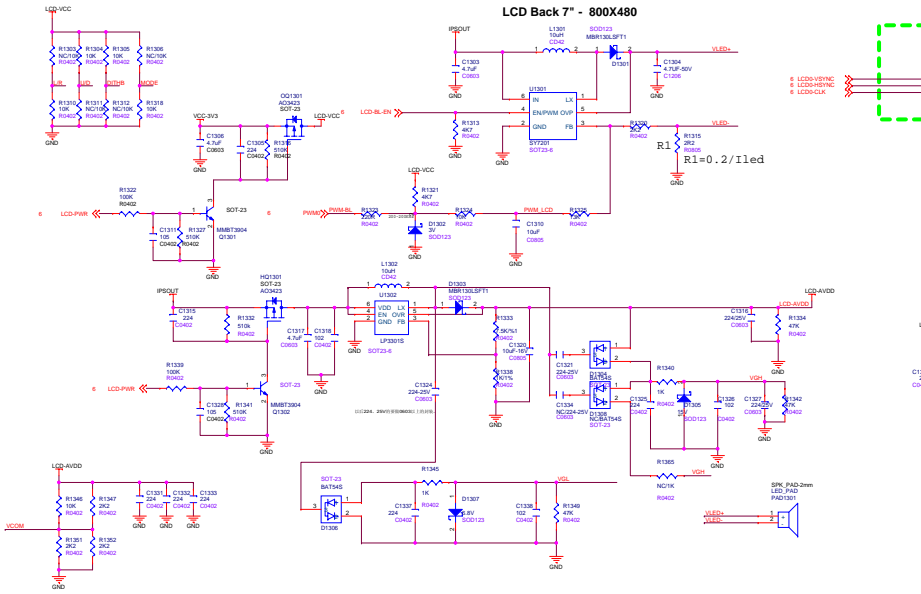


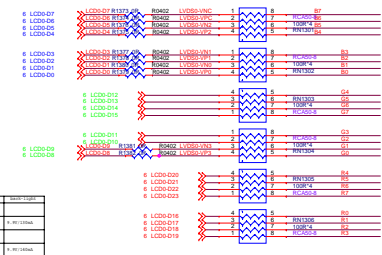
LCD

LCD Back 7" - 800X480

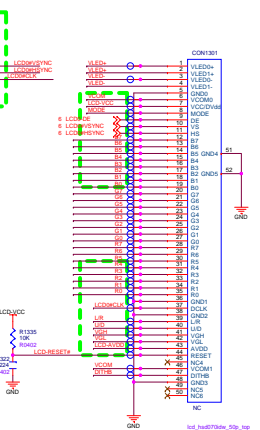


电压对照表

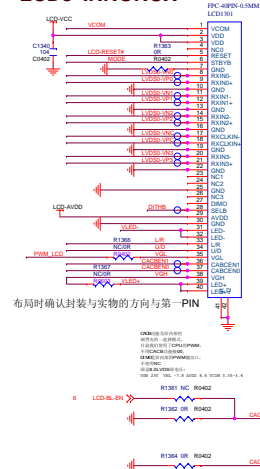
电压	10V	5V	3.3V	1.8V	1.5V	1.2V	0.9V	0.6V	0.3V	0.1V
LED_VDD0	10.00	5.00	3.30	1.80	1.50	1.20	0.90	0.60	0.30	0.10
LED_VDD1	10.00	5.00	3.30	1.80	1.50	1.20	0.90	0.60	0.30	0.10
LED_VDD2	10.00	5.00	3.30	1.80	1.50	1.20	0.90	0.60	0.30	0.10
LED_VDD3	10.00	5.00	3.30	1.80	1.50	1.20	0.90	0.60	0.30	0.10



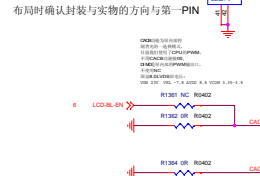
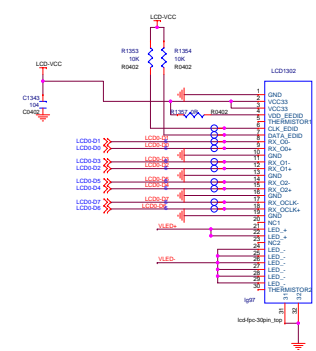
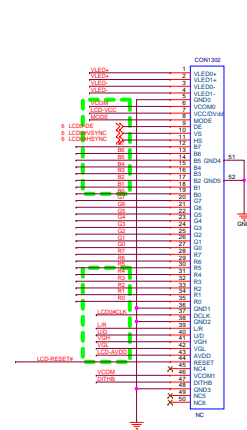
LCD7" INNONUX



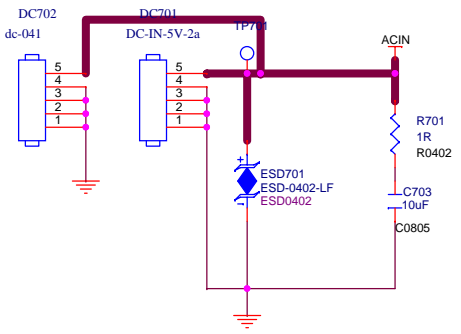
LCD8" INNONUX



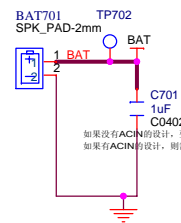
LCD8" INNONUX



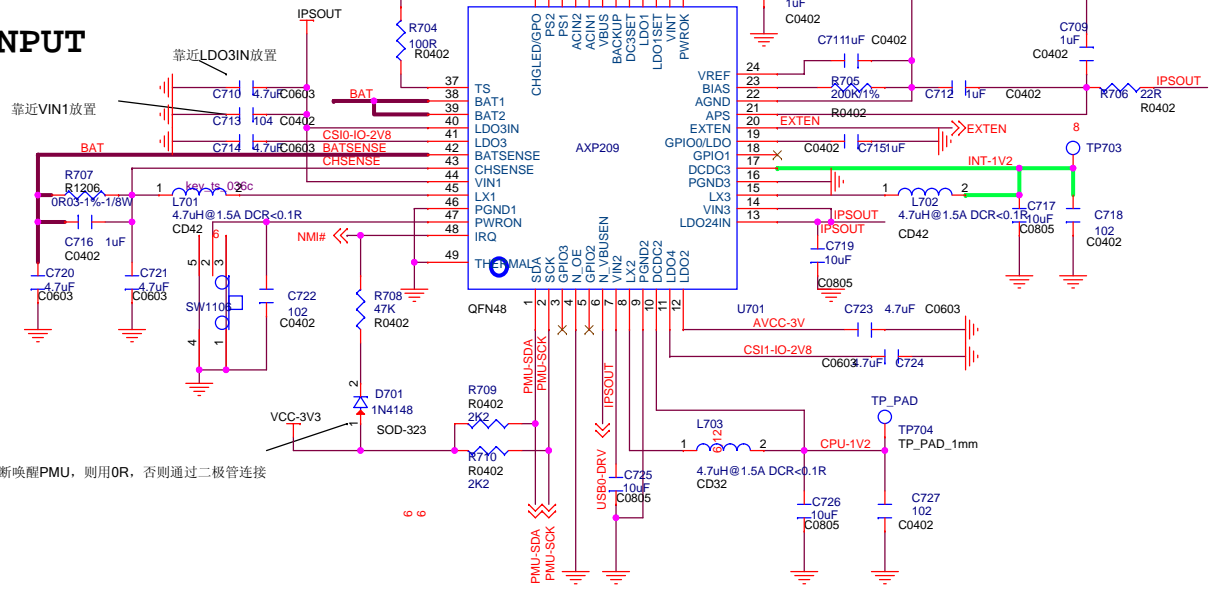
POWER-PMU



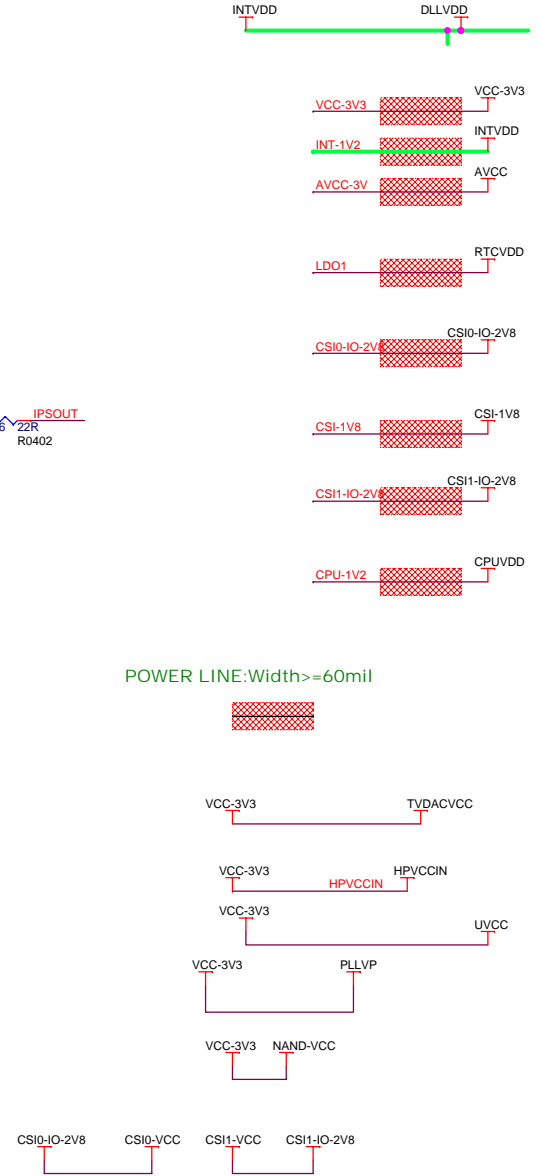
此时不支持电池温度检测



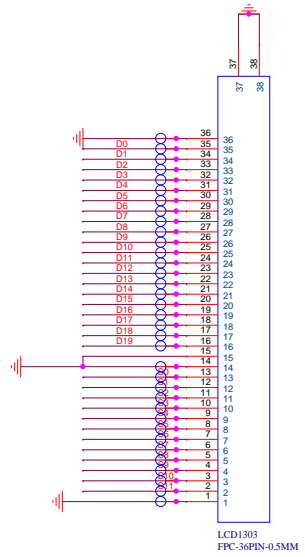
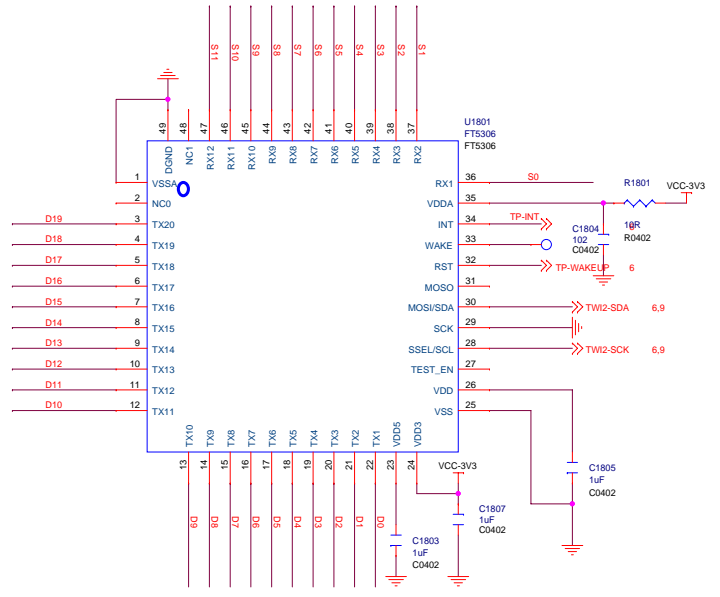
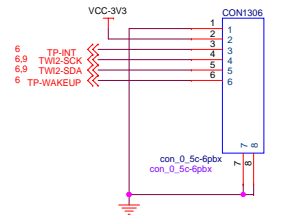
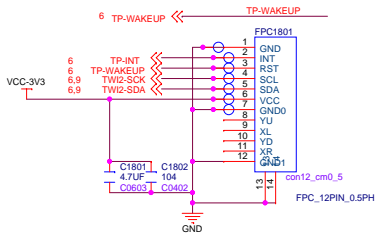
POWER INPUT



如果不使用中断唤醒PMU, 则用OR, 否则通过二极管连接

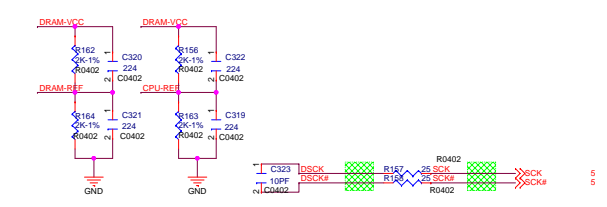
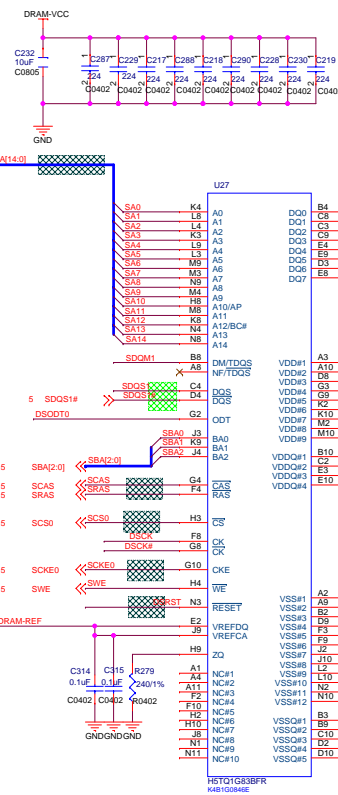
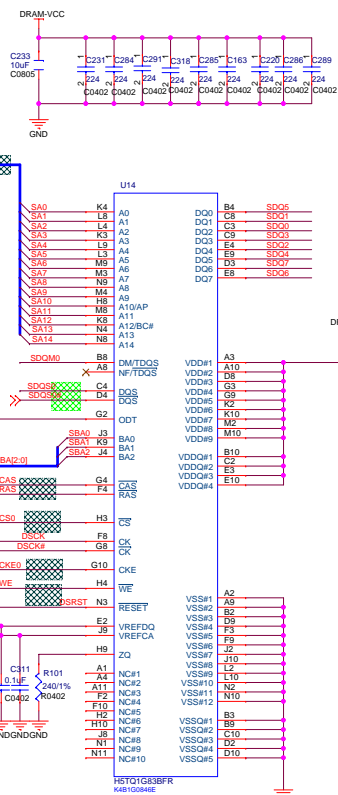


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POWER-PMU			
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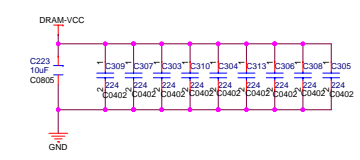
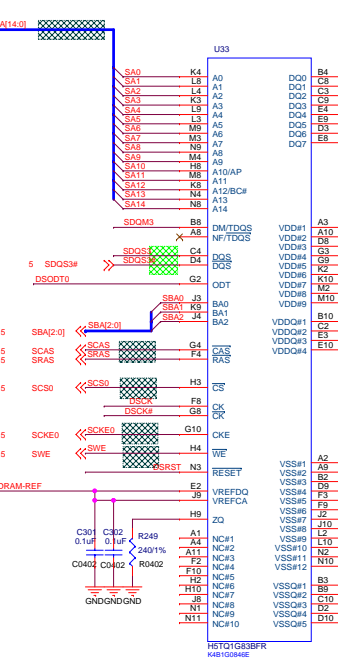
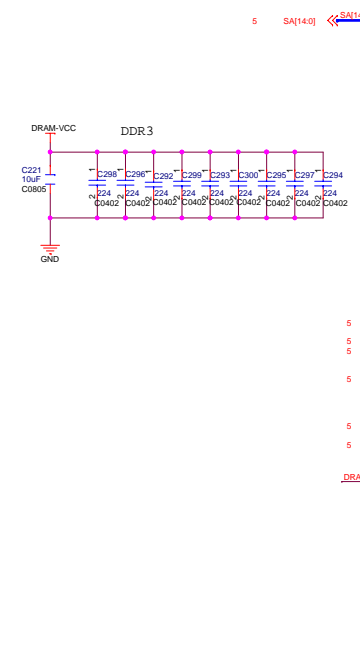
DDR3 8bit x 4ea

DDR封装为TFBGA82



Differential pairs
Z0= 100 ohm

Equilong BUS
Z0= 50 ohm

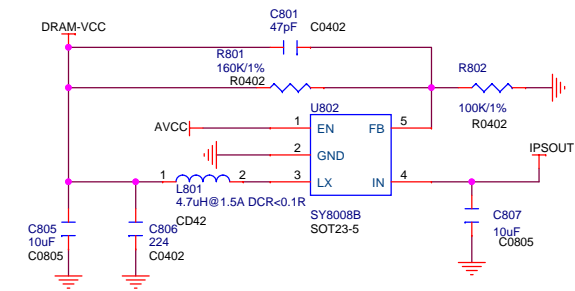


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POWER-DC/DC

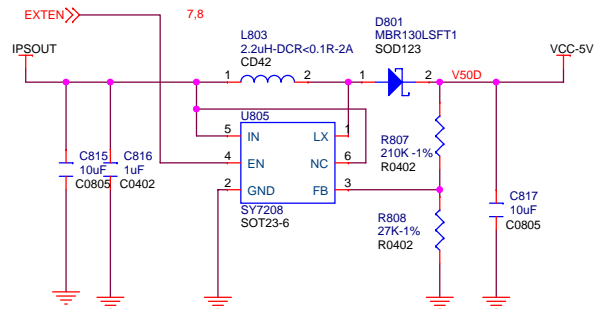
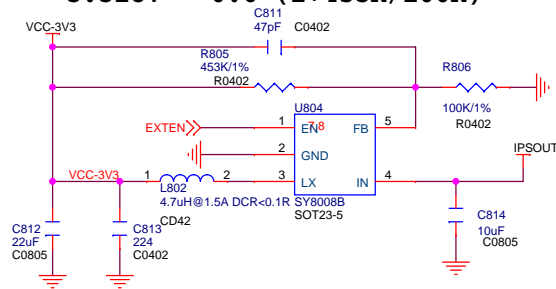
1. 电池充电电感: L1在value标注"4.7uH@1.5A DCR<0.1R"
2. CPU 1.2V电感: L2在value标注"4.7uH@1.5A DCR<0.1R"
3. CPU 1.2V电感: L3在value标注"4.7uH@1.5A DCR<0.1R"
4. VCC-3V3电感: L6在value标注"4.7uH@1.5A DCR<0.1R"
5. DRAM-VCC电感: L11在value标注"4.7uH@1.5A DCR<0.1R"
6. OTG升压电感: OL2在value标注2.2uH@2A DCR<0.1R

备注: xuH@xA表示在xA的电流下电感感量还满足xuH, DCR<0.1R表示电感直流电阻要小于0.1欧姆。
 请将所有电感封装都改为CD43, CD32大多数情况下饱和电流不满足目前方案的应用要求。



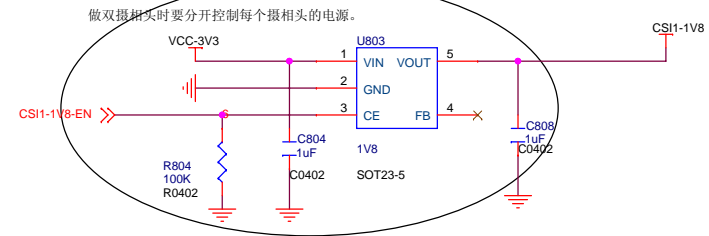
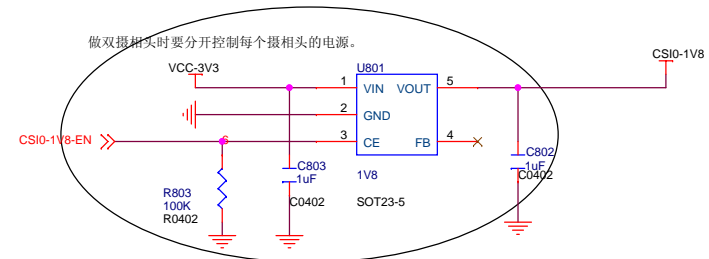
$$V_{out} = 0.6 * (1 + R1/R2)$$

$$3.318V = 0.6 * (1 + 453K/100K)$$



$$V_{out} = 0.6 * (1 + R1/R2) \quad \text{实际输出控制在5.2V}$$

$$5.26V = 0.6 * (1 + 210K/27K) \quad \text{实际输出控制在5.26V}$$



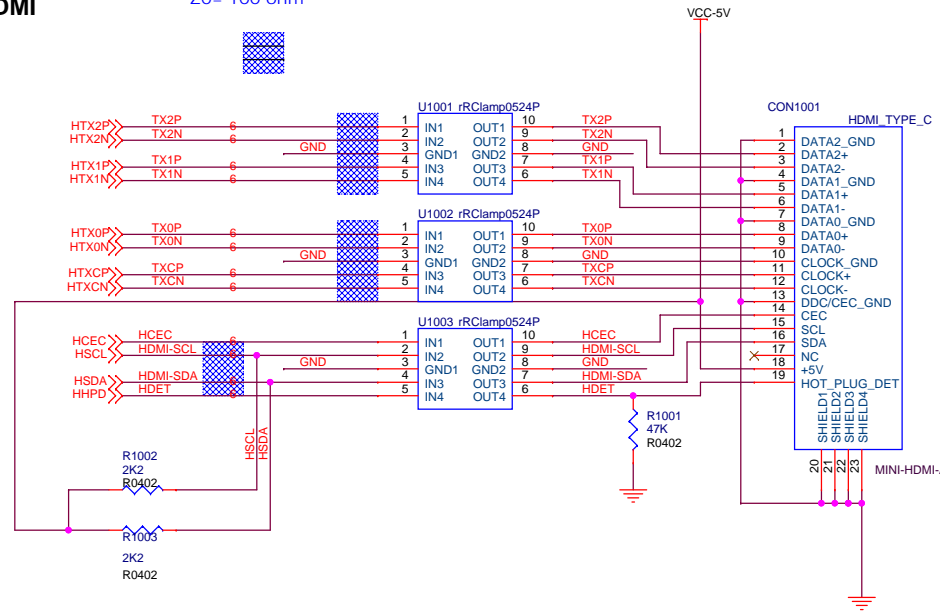
MAINCHIP_PAD_DDR3			
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HDMI-CSIO

HDMI

HDMI

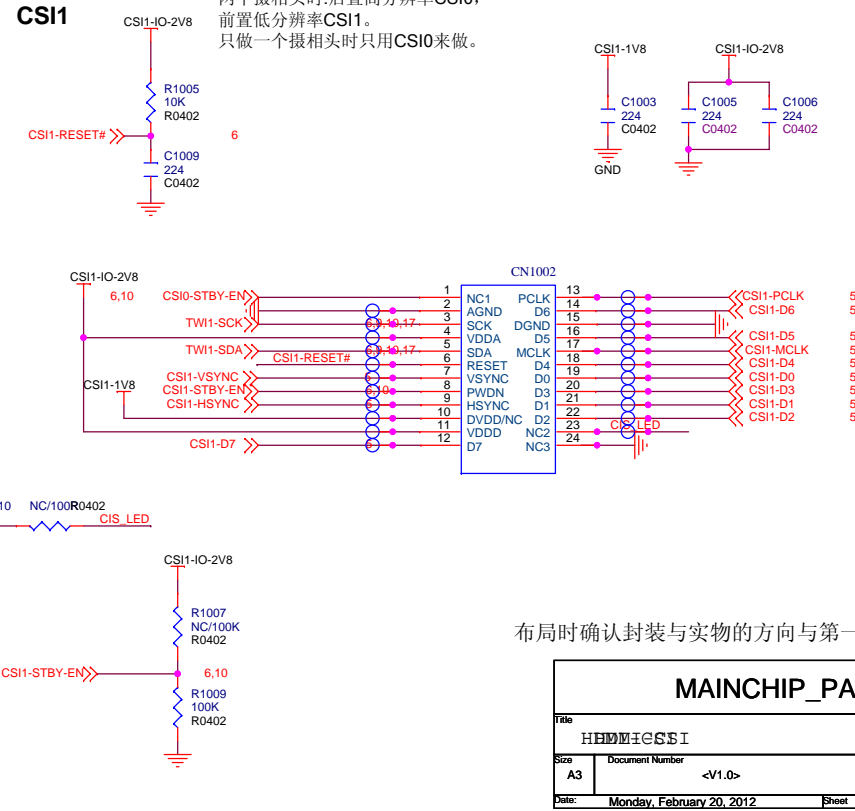
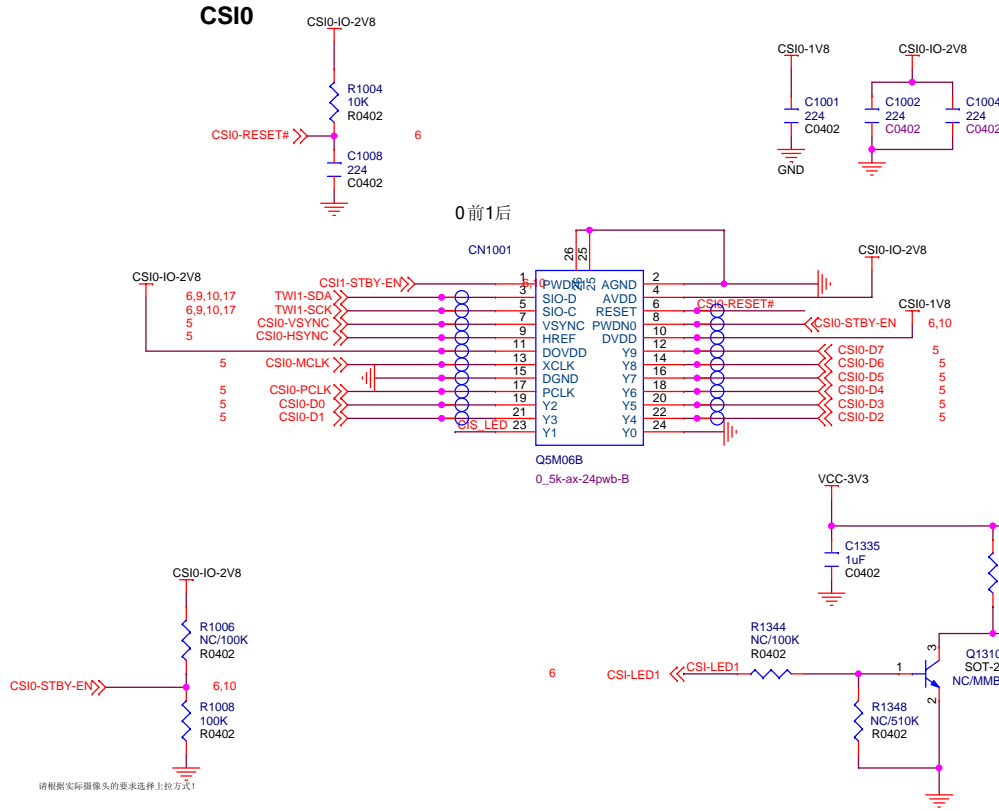
Differential pairs
Z0= 100 ohm



CSIO

CS11

两个摄像头时:后置高分辨率CSIO,
前置低分辨率CS11。
只做一个摄像头时只用CSIO来做。



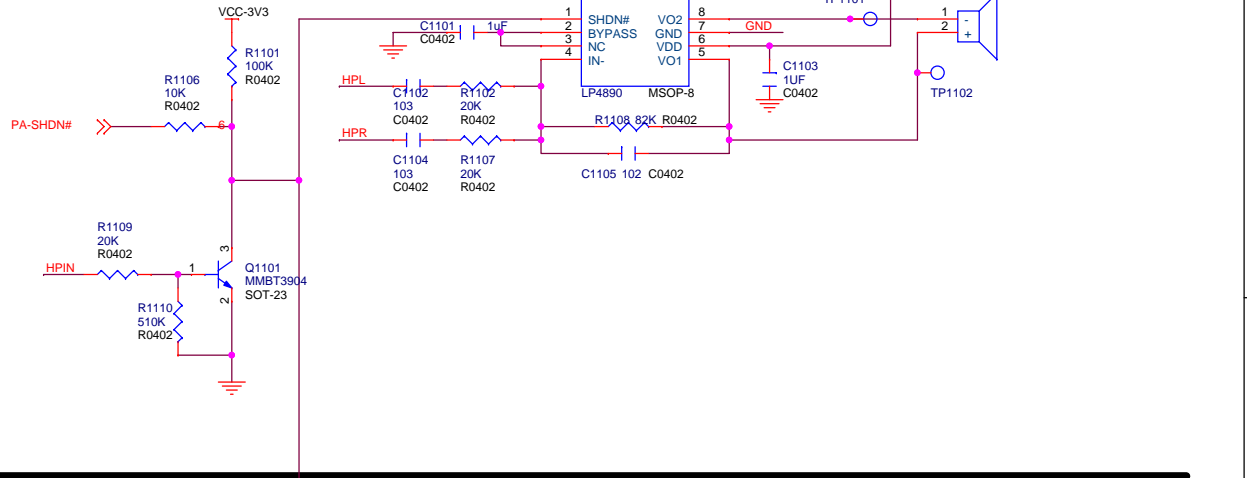
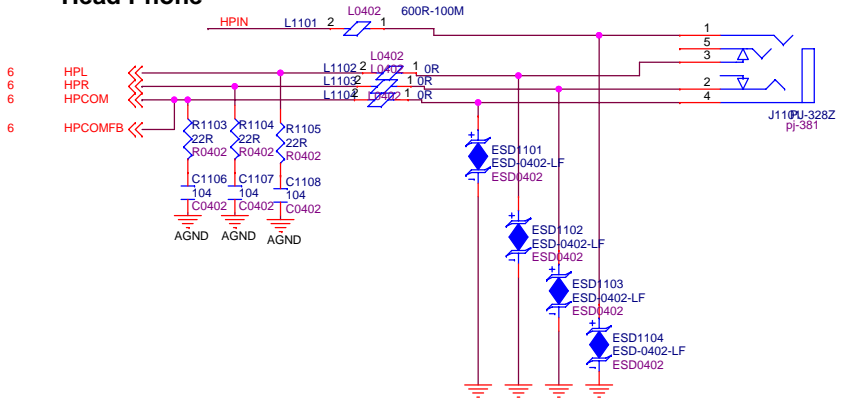
布局时确认封装与实物的方向与第一PIN

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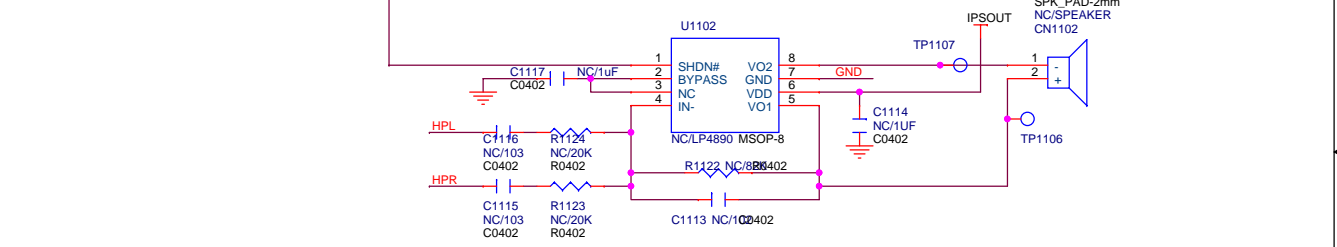
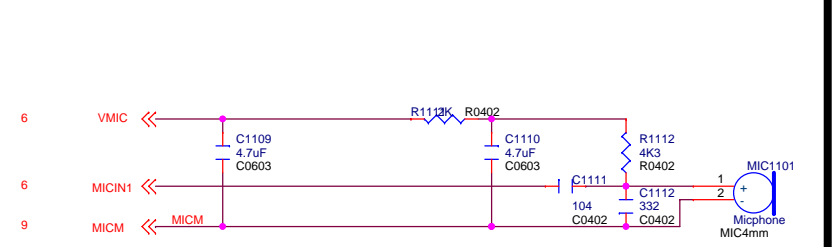
请根据实际摄像头的要求选择上拉方式1

HP-KEY-MIC-IR-TVOUT

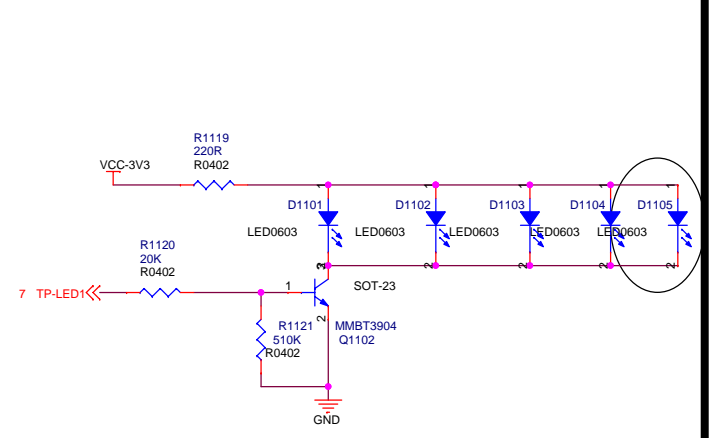
Head Phone



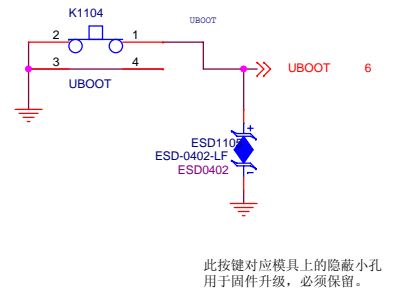
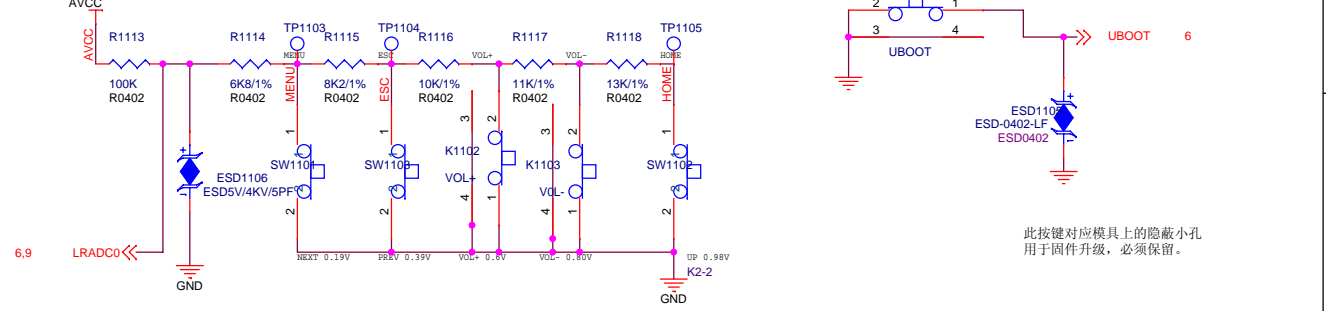
Microphone



IR MODULE



KEY

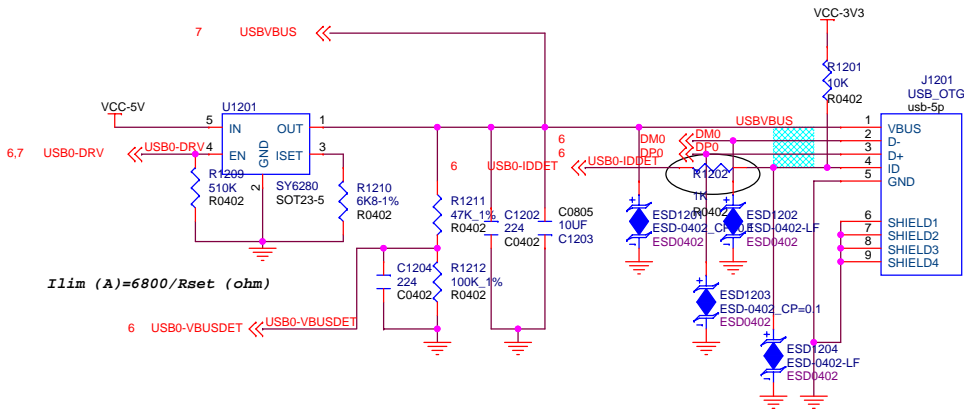


此按键对应模具上的隐藏小孔
用于固件升级，必须保留。

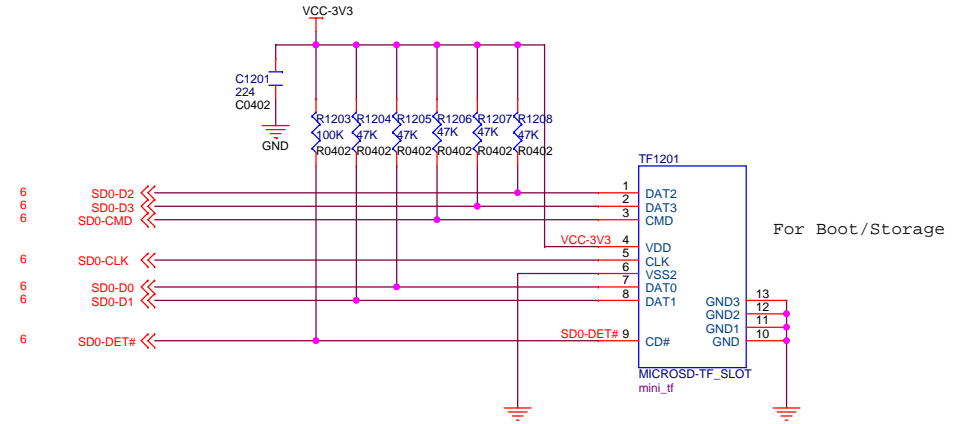
MAINCHIP_PAD_DDR3			
File	HP-KEY-MIC-IR-TVOUT		
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USB-CARD

USB_OTG



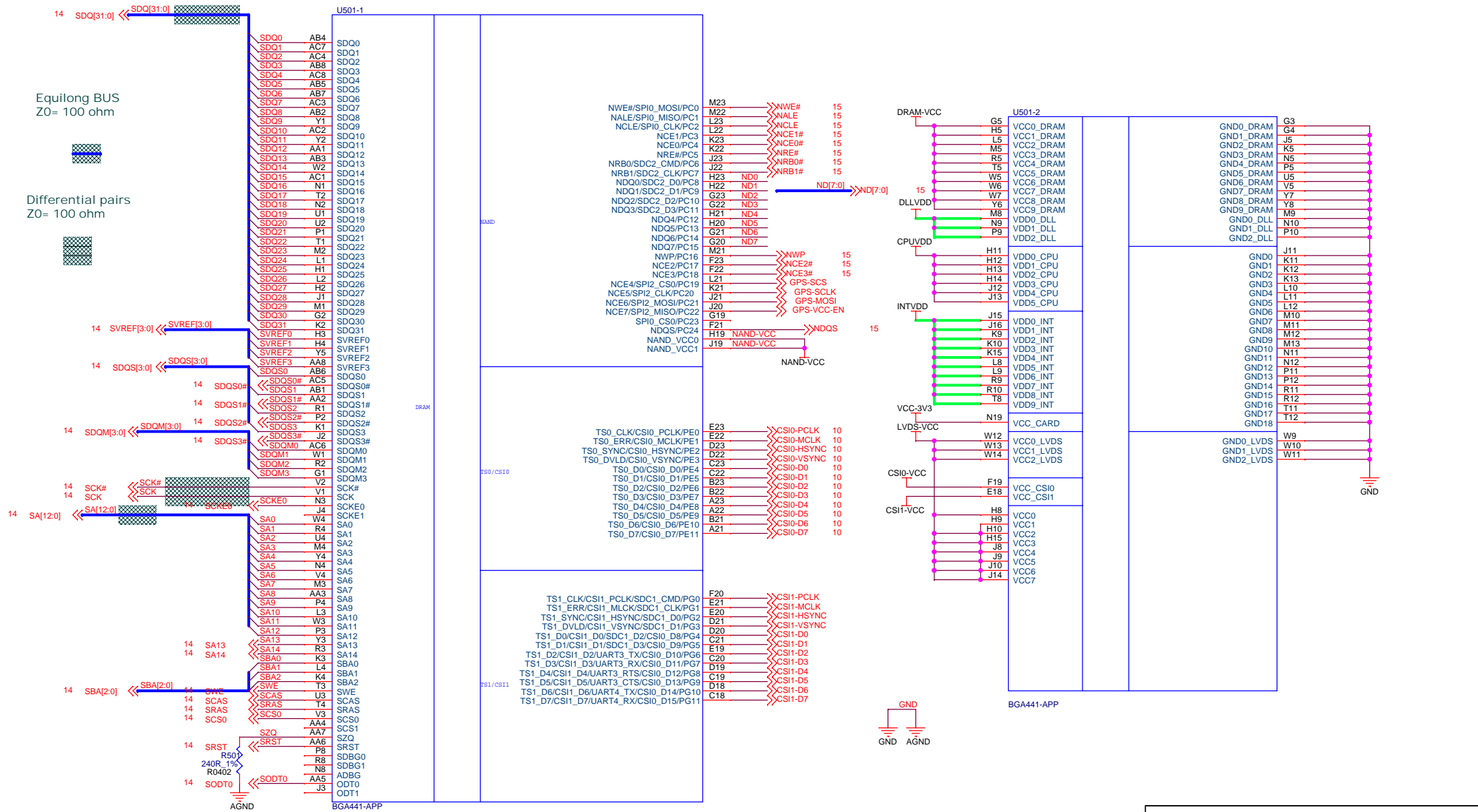
CARD0



==

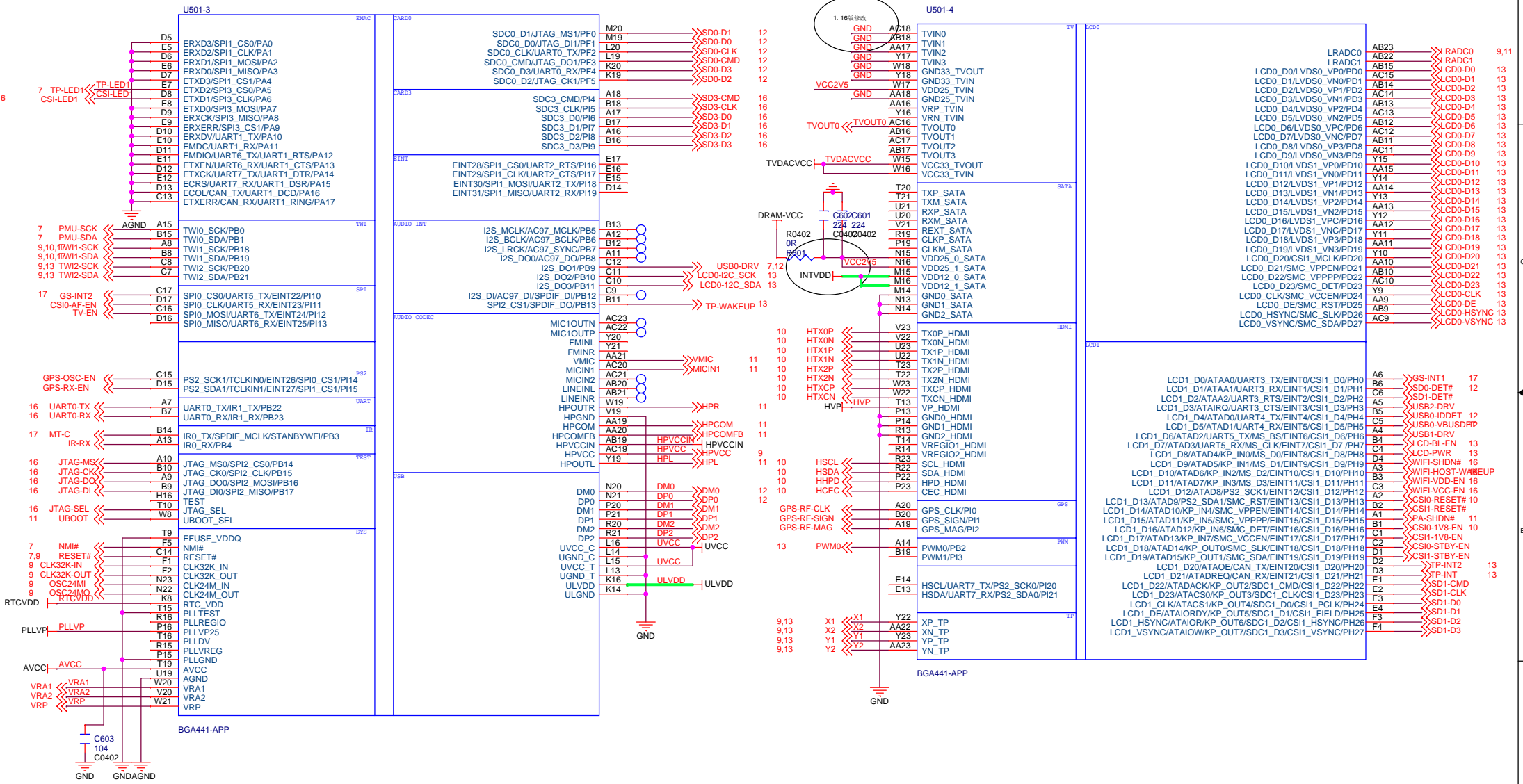
MAINCHIP_PAD_DDR3			
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CPU1



MAINCHIP_PAD_DDR3			
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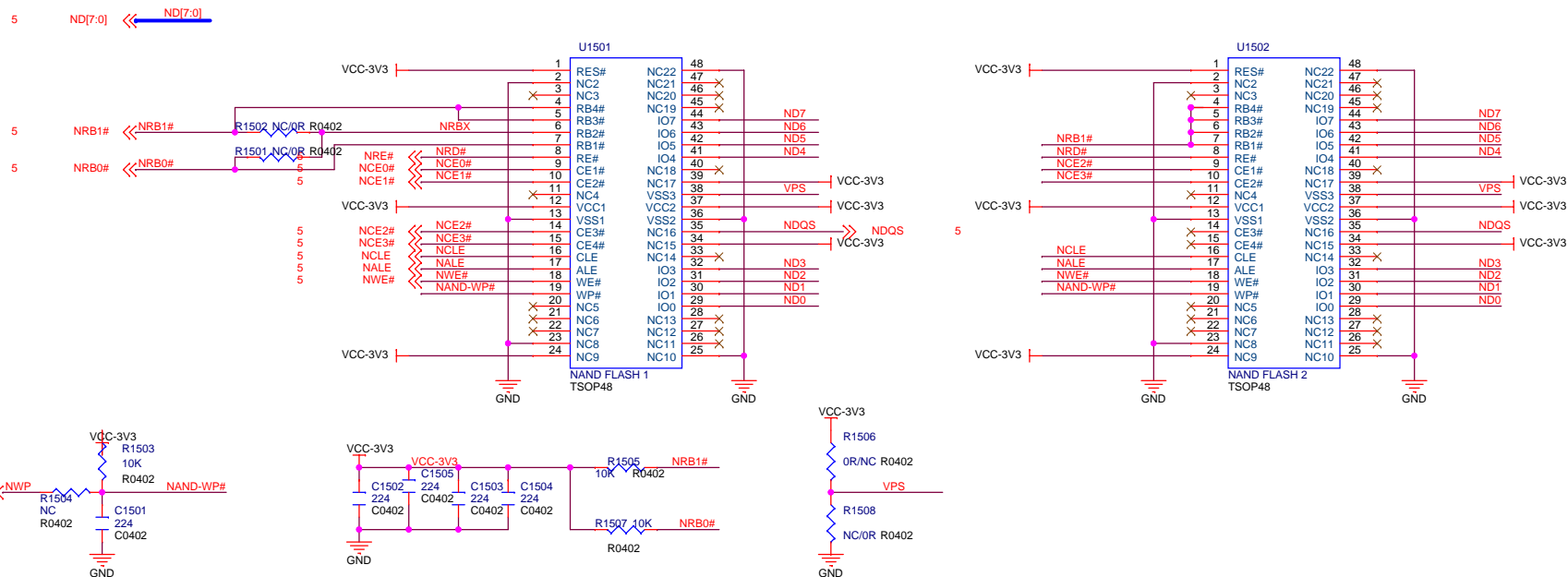
CPU2



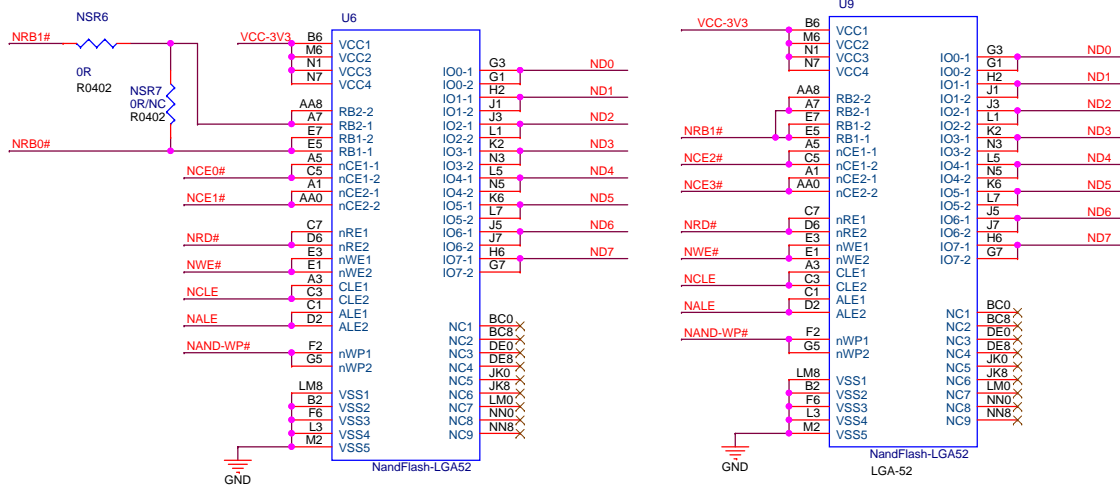
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NAND Flash

TSOP-48 Nand



LGA-52



- (1) 接1片单片选Nand 时, NSR2、NSR1断开
- (2) 接1片双片选Nand 时, 连接NSR2, 断开NSR1
- (3) 接1片四片选Nand 时, 连接NSR1, 断开NSR2
- (4) 接2片单片选或接2片双片选Nand时, 连接NSR1, 断开NSR2
- (5) 接Intel、Toshiba、Samsung 2xnm TSOP Nand时, NSR4连接, NSR5断开; 其它的NSR4断开, NSR5连接

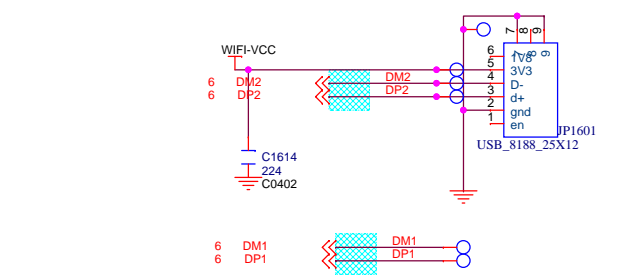
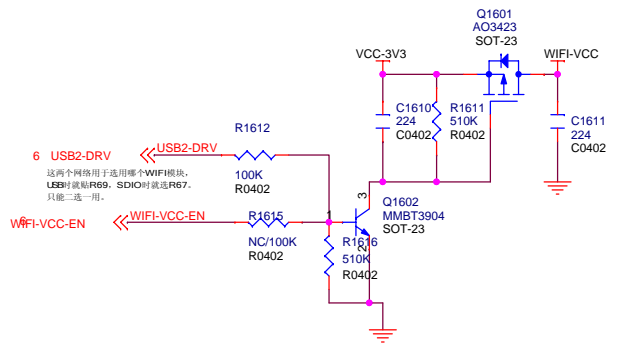
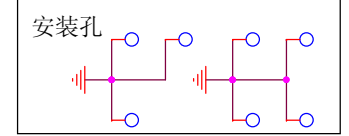
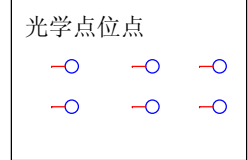
MAINCHIP_PAD_DDR3

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DEBUG



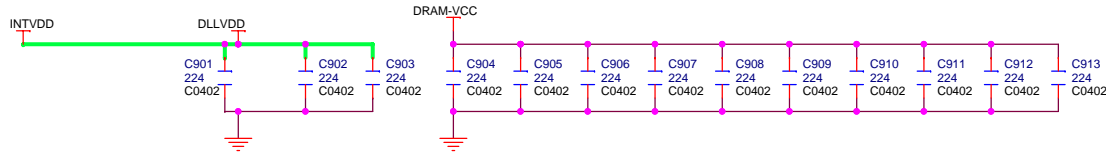
预留DEBUG测试点，以备调试使用



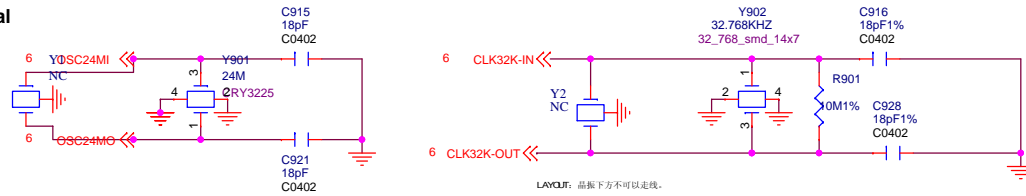
MAINCHIP_PAD_DDR3			
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BESIDE CPU

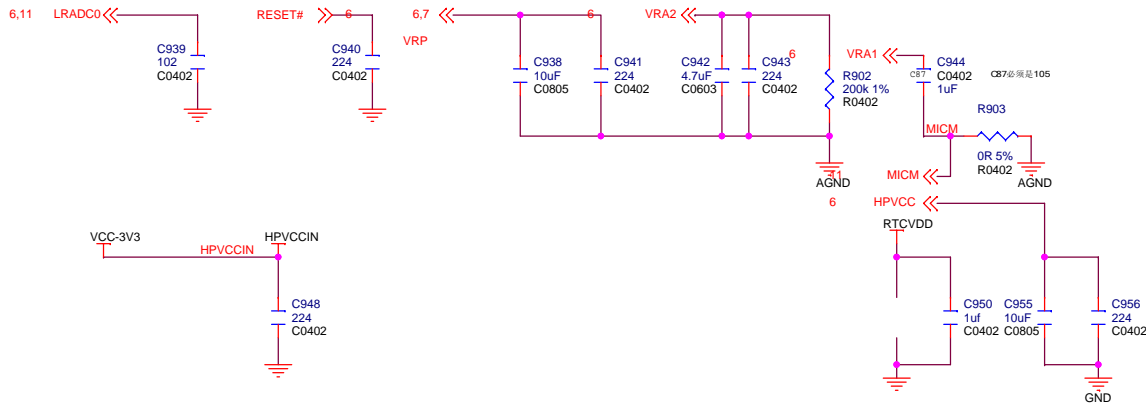
DRAM



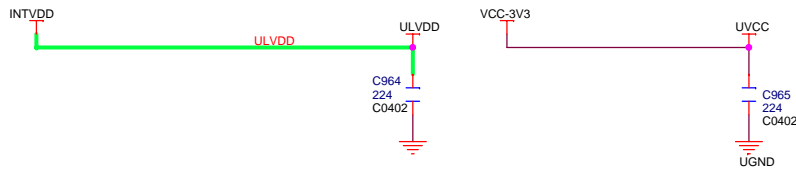
Crystal



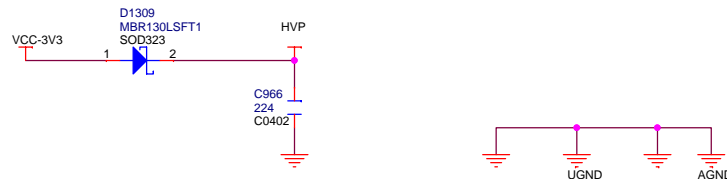
AUDIO&SYS&TP



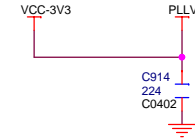
USB



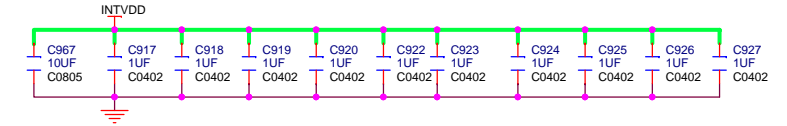
HDMI



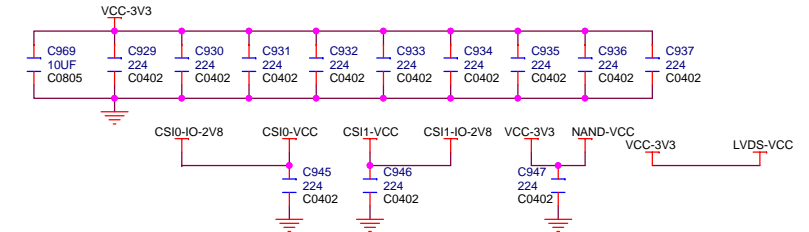
PLL



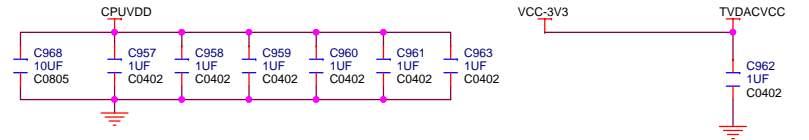
CORE



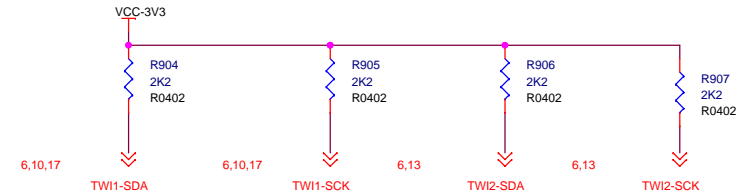
PIO-INTERFACE



CPU&TV



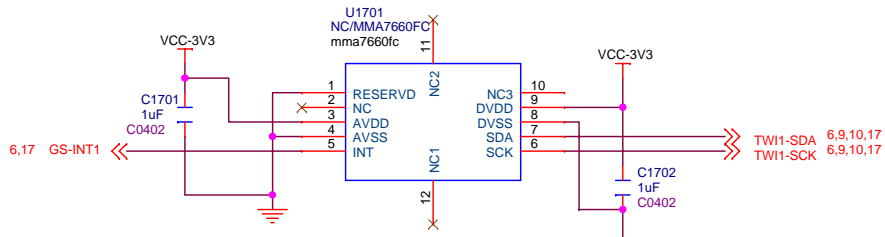
TWI-PULLUP



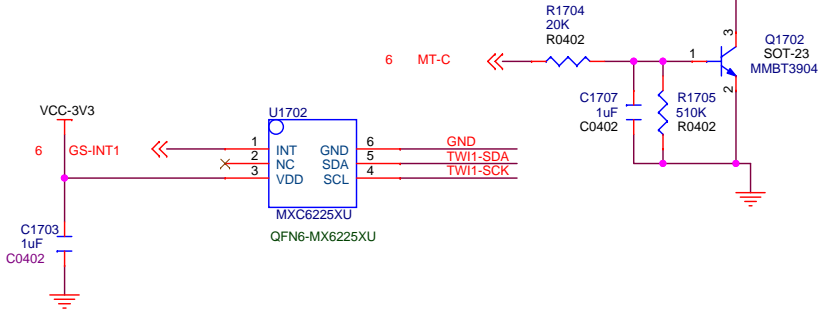
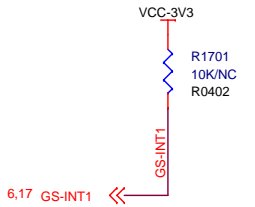
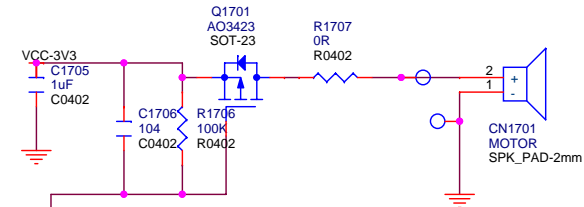
MAINCHIP_PAD_DDR3

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G-SENSOR



摆放时务必注意G-Sensor在背对屏幕的那面，PIN 1朝屏幕左上角



右上方放置PIN1脚，与屏平行放置，放在屏的左上方

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